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Aehr Test Systems Announces Order for ABTS-Pi™ Burn-in and Test System from new Semiconductor Manufacturing Customer in China

Fremont, CA (November 6, 2017) - Aehr Test Systems (Nasdaq: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it has received an order for its Advanced Burn-in and Test System (ABTS) from a new customer in China. This system is expected to ship in Aehr Test's fiscal 2018 fourth quarter.

Gayn Erickson, President and CEO of Aehr Test Systems, said, "This initial order from a new customer in China represents our 10th customer in China and continues our expansion and success in the growing China market. We believe that the customer selected our ABTS-Pi solution for its quality, reliability and outstanding performance. Aehr offers highly capable direct local support to our customers in China, helping customers to get the most from their ABTS systems. The system will be used for reliability testing of this customer's semiconductor devices, including life tests. The ABTS-Pi model was selected because the customer's high-power devices require individual temperature control per device, and the ABTS-Pi systems have a market-leading capacity in this mode."

According to the Semiconductor Industry Association (SIA), China chip sales are expected to grow 25% YoY in 2017 and in 2018, China is expected to overtake Taiwan to become the second largest Semiconductor producer (Korea is first). SEMI projects Semiconductor Manufacturing Equipment sales in China to grow 61% in 2018.

"China continues to accelerate its growth in semiconductor manufacturing and increased production infrastructure and testing capacity, and we see significant opportunities for continued expansion in this growing market with our innovative burn-in and test systems," Erickson concluded.

Aehr Test's ABTS family of products is based on a state-of-the-art hardware and software platform that is designed to address not only today's devices, but also future devices for many years to come. It can test and burn-in both logic and memory devices and includes resources for high pin-count devices and configurations for high-power and low-power applications. ABTS systems can be configured with up to 72 burn-in boards, up to 320 I/O channels, 32M of test vector memory per channel and up to 16 independent device power supplies. The ABTS system can be configured with a scalable cost-effective individual device temperature control solution for up to 64 devices per burn-in board and up to 75 watts per device or more. Individual temperature control enables high-power devices with a broad range of power dissipation to be burned-in simultaneously in a single burn-in chamber while maintaining a precise device temperature. The

ABTS system also uses N+1 redundancy technology for many key components in the system to maximize system uptime.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS and FOX-P™ families of test and burn-in systems, the FOX WaferPak™ Aligner, FOX-XP WaferPak Contactor, and FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP™ system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak Contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System's website at www.aehr.com.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding expected shipping dates of our ABTS systems and uses of our ABTS systems. The risks and uncertainties that could cause our results to differ materially from those expressed or implied by such forward-looking statements include, without limitation, general world economic conditions and events, the state of the semiconductor equipment market, our ability to maintain sufficient cash to support operations, acceptance by customers of the ABTS technology, acceptance by customers of the ABTS systems shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described. See Aehr Test's recent 10-K and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing our business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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